14th IEEE CPMT Symposium Japan (ICSJ2025)

The Leading International Components, Packaging and Manufacturing Technology Symposium

November 12-14, 2025
Ritsumeikan University's Suzaku Campus, Kyoto, Japan

Advance Program (Last update: October 30, 2025)

November 12, 2025 (Wednesday)

	4F/5F Main Hall		1F Room I		1F Room II	
9:00	*Registration*					
10:10	*Opening Remark (General Chair, Hideyuki Nawata)*					
10:25	*Greeting speech (IEEE EPS President-Elect, Jeffrey Suhling)*					
10:35	*Award Ceremony*					
10:50-12:30	**Plenary Speech I & II** **Hall I** **Hideyuki Nasu (Furukawa Electric Co., Ltd.) and Takaaki Ishigure (Keio University)**					
10:50	**Plenary Speech I: "Nothing" is Better than Silica** ***Sir David Neil Payne (University of Southampton)***					P-01
11:40	**Plenary Speech II: Paradigm Shifts in Silicon Photonics** ***Roel Baets (Ghent University - imec)***					P-02
12:40-12:55			*Sponsor's Seminar 1 (with a light meal) @1F Room I* *Nanoscribe GmbH & Co. KG*			
12:55-13:10			*Sponsor's Seminar 2 (with a light meal) @1F Room I* *Hakusan Inc.*			
13:30-15:25	**Session 1: Photonics I** **(Photonics Packaging / Si Photonics / Optical Waveguide)** **Chairperson** **Hidetoshi Numata (IBM Research - Tokyo)** **Peter O'Brien (Tyndall National Institute)**		**Session 2: Process and Material Technologies for Hybrid Bonding** **Chairperson** **Shinya Takyu (LINTEC Corporation)** **Satomi Kawamoto (NAMICS Corporation)**		**Session 3: High-Speed Package and System (Signal and Power Integrity)** **Chairperson** **Kazuyuki Nakagawa (Renesas Electronics Corporation)** **Yutaka Uematsu (Hitachi, Ltd.)**	
13:30	**(Invited)** Co-Design and Co-Process for Co-Packaged Optics - An End-To-End Development Solution *Christopher Striemer* *AIM Photonics*	01-01	**(Invited)** "Solution Proposal and Discussion on C2W-HB Toward to Practical Use" ～Introduction of Polymer Dielectric and Mounting Technology～ *Takenori Fujiwara* *Toray Industries, Inc.*	02-01	**(Invited)** Inductors in Power over Signal (PoC and PoDL) for In-Vehicle Networks *Thomas Schamberger* *TDK Electronics AG*	03-01
13:55	Underfill with High Thermal Conductivity in Silicon Photonic Chiplets for Co-Packaged Optics (CPO) Devices *Dai-Fei Li, Wen-Yu Teng, Liang-Yih Hung, Andrew Kang, Yu-Po Wang, Don-Son Jiang* *Siliconware Precision Industries Co., Ltd.*	01-02	**(Invited)** Direct Transfer Bonding Overcoming the Challenges of Integrating delicate and Ultra-Thin Chips with 50-nm Scale Accuracy *Ichiro Sano* *TAZMO CO., LTD.*	02-02	Ultra-Small 145 GHz Coaxial Connector: Edge-Mount PCB Integration and Performance *Hitoshi Onoduka, Yu-Cen Sun, Yushi Kirii* *Yuetsu Seiki Co.,Ltd*	03-02
14:20	Development of Simultaneous Electrical and Optical Mounting for Co-Packaged Optics Modules *Hisaaki Nishimura, Mizuki Tonomura, Misa Takahashi, Akari Watanabe, Megumi Oishi, Fumiaki Haraguchi, Tokuro Ozawa, Takeshi Yokoyama, Tomoyuki Akahoshi* *KYOCERA Corporation*	01-03	**(Invited)** Design and Development of Carrier Tapes for Direct Transfer Bonding Process *Tomoka Kirihata* *LINTEC Corporation*	02-03	Effect of Thermal Distribution on Signal and Power Analysis of Large Complex 3D-IC System *Yu Tomonaga, Tejas Jeurkar, Anushruti Jaiswal* *ANSYS, Inc. and Ansys Japan K.K.*	03-03
14:45	Extremely low bending loss (<0.5 dB at 1-mm bending radius) GI core polymer optical waveguide *Masahiro Karakawa[1], Takaaki Ishigure[2]* *1) Ajinomoto Co., Inc.* *2) Keio University*	01-04	Chemical resistant dicing tape for hybrid bonding process *Ryoh Takahashi, Koki Maruno, Kazutoshi Furuzono, Naoki Takahara, Seiji Kai* *Resonac Corporation*	02-04	*Interview with the Authors (Discussion after the session) + Sponsor's Exhibition*	
15:10	*Interview with the Authors (Discussion after the session) + Sponsor's Exhibition*					
15:25	*Coffee break + Sponsor's Exhibition*					
15:40-17:35	**Session 4: Photonics II** **(Laser)** **Chairperson** **Nobuo Ohata (Mitsubishi Electric Corpolation)** **Richard Pitwon (Resolute Photonics)**		**Session 5: Next Generation Packaging Technologies I** **Chairperson** **Eiji Higurashi (Tohoku University)** **Naoko Araki (Daicel Corporation)**		**Session 6: High-Speed / RF Package and System** **Chairperson** **Yoichiro Kurita (Tokyo Institute of Technology)** **Wataru Shiroi (Renesas Electronics Corporation)**	
15:40	**(Invited)** Optical Signal Processsing (OSP) for pluggable transcedivers and co-packaged optics (CPO) *Yosef Ben Ezra* *Newphotonics*	04-01	New Optical Adhesive Design for CPO Packaging Solution *Fumiya Suzuki, Masashi Kajiwara, Takashi Yamaguchi, Masayoshi Otomo, Noriyuki Sakai* *NAMICS CORPORATION*	05-01	Radiation-Induced Destructive Effects on COTS FPGA in GEO Satellite Environments *Yuzo Yajima[1], Eisuke Haraguchi[1], Shigenori Tani[1], Hiroshi Kinoda[1], Hiroaki Miyake[2]* *1) Mitsubishi Electric Corporation* *2) Tokyo City University*	06-01
16:05	Ultrathin Chips of III-V Bonding Process Using Laser Peel Transfer Technology for Co-Packaged Optics *Haruka Fujishige[1], Takumi Ikehara[1], Tatsuya Okada[1], Yoshiaki Arai[1], Junpei Oniki[2], Daichi Miyazaki[2], Takenori Fujiwara[2], Yukari Jo[2]* *1) Toray Engineering, Co. Ltd.* *2) Toray Industries, Inc.*	04-02	High I/O Density Solution on Flip Chip Substrate for Advanced Package *Yuan Chang Ni[1], Hung Kun Chen[1], Yu Cheng Pai[1], Cheng Yu Kang[1], Jen Shang Chen[2], Wei Ching Chu[2], Yu-Po Wang[1], Don-Son Jiang[1]* *1) Siliconware Precision Industries Co., Ltd.* *2) KINSUS INTERCONNECT TECHNOLOGY CORP*	05-02	Efficient Integral-Equation Methodology for Signal Integrity Analysis of Large-Scale IC Packages *Hans Schreckenbach, Santosh Janaki Raman, Lucas Banting, Nima Chamanara, Andre Fecteau, David Abraham, Max Hughson, Nick Geddert, Troy Lowry, Jonatan Aronsson* *CEMWorks Inc.*	06-02
16:30	An 8-Channel MM VCSEL-Based Linear Drive CPO Transceiver for Compute and Backend Interconnects in AI/ML Systems *Sho Yoneyama, Wataru Yoshida, Kazuya Nagashima, Kensho Nishizaki, Hideyuki Nasu* *Furukawa Electric Co., Ltd.*	04-03	Development of heat-resistant UV-curable dicing tape *Reo Ozeki, Sayaka Tsuchiyama, Akio Fukumoto* *LINTEC corporation*	05-03	An Adjustable Energy-Recovering Electrical-Balance Duplexer for In-Band Full-Duplex Transceivers in the 6G FR3 Band *Hsin-Chieh Lin[1], Chih-Hao Chuang[2], Yan-Qi Weng[2], Da-Chiang Chang[1], Hwann-Kaeo Chiou[2]* *1) National Institutes of Applied Research* *2) National Central University*	06-03
16:55	**(Invited)** Chip-Scale Comb Lasers for Co-Packaged Optics *Frank Smyth, M. Deseada Gutierrez, Shane Duggan, Alison Kearney, Chris McGuinness, Amol Delmade* *Pilot Photonics Ltd*	04-04	*Interview with the Authors (Discussion after the session) + Sponsor's Exhibition*			
17:20	*Interview with the Authors (Discussion after the session) + Sponsor's Exhibition*					
17:35-18:15	**Special Speech I** **Hall I** **Chairperson Shinya Takyu (LINTEC Corporation) and Hideyuki Nawata (Nissan Chemical Corporation)**					
17:35	**Special Speech I: Artifact Metrics and Individual Management of Semiconductor Packages** ***Tsutomu Matsumoto (AIST)***					S-03
19:15	*Welcome Reception*					
21:15	*Close*					

November 13, 2025 (Thursday)

	4F/5F Main Hall		1F Room I		1F Room II	
9:00			*Registration*			
9:20	*Guest speech (President of Ritsumeikan University, Yoshio Nakatani)*					
9:30- 10:20	**Plenary Speech III** **Hall I** **Chairperson Shoji Uegaki (Crane Research) and Taiji Sakai (TSMC Japan 3DIC R&D Center, Inc.)**					
9:30	**Plenary Speech III : Challenges and Opportunities for Japan Ecosystem in CoWoS® Technology Development for Further Evolution of AI** ***Shimpei Yamaguchi (TSMC Japan 3DIC R&D Center)***					P-03
10:20	*Coffee break + Sponsor's Exhibition*					
10:30- 12:00	**Session 7: Advanced PKG I** **Chairperson** **Taiji Sakai (TSMC Japan 3DIC R&D Center, Inc.)** **Chinami Marushima (IBM Japan, Ltd.)**		**Session 8: Next Generation Packaging Technologies II** **Chairperson** **Jun Maeda (LINTEC Corporation)** **Satomi Kawamoto (NAMICS Corporation)**			
10:30	**(Invited)** Graphite sheet embedded in an organic flip-chip package for heat spreading *Keiji Matsumoto* *IBM Research-Tokyo*	07-01	Extraction Techniques of Dielectric Characterization of Materials up to E-band Frequency *Chia Chu Lai, Ho-chuan Lin, Vito Lin, Andrew Kang, Yu Po Wang, Don-Son Jiang* *Siliconware Precision Industries Co., Ltd.*	08-01		
10:55	Digital-Twin-Driven Machine Learning for Thermal Optimization of Flip-Chip Packages *Mohammad Rafiee, Vysak Vijayan Nair* *University of Ottawa*	07-02	Measurement and Analysis of Substrate Integrated Waveguide Using Low Temperature Co-fired Ceramics at 250 GHz *Nobuki Hiramatsu1), Hiroshi Uchimura1), Tuchjuta Ruckkwaen1), Masahiro Tomisako1), Kouhei Hirose1), Naoki Hirayama1), Issei Watanabe2), Kunio Sakakibara3)* *1) KYOCERA Corporation* *2) National Institute of Information and Communications Technology* *3) Nagoya Institute of Technology*	08-02		
11:20	Generation of the thermal digital twin model for an IC chip *Shuainan Lin1), Yanbo Tang1), Jiajia Sui2), Chi, Chun-An2), Boping Wu1), Cheng Yang1), Harvey Jin3), Fay Cui3), Jonny Wang3)* *1) JCET Group Co., Ltd.* *2) Shanghai Southchip Semiconductor Technology Co., LTD* *3) Siemens industry software Co., Ltd*	07-03	*Interview with the Authors (Discussion after the session) + Sponsor's Exhibition*			
11:45	*Interview with the Authors (Discussion after the session) + Sponsor's Exhibition*					
12:00- 12:15			*Sponsor's Seminar 3 (with a light meal) @1F Room I* *SURUGA SEIKI CO.,Ltd.*			
12:15- 12:30			*Sponsor's Seminar 4 (with a light meal) @1F Room I* *SENKO Advance Co., Ltd.*			
12:30- 12:45			*Sponsor's Seminar 5 (with a light meal) @1F Room I* *Vanguard Automation GmbH*			
13:00- 14:55	**Session 9: Advanced PKG II** **Chairperson** **Kenji Takahashi (AIST)** **Kiyokazu Yasuda (The University of Osaka)**		**Session 10: Photonics III** **(Optical Waveguide)** **Chairperson** **Geert Van Steenberge (IMEC and Ghent University)** **Motohito Takezaki (Hakusan Inc.)**		**Session 11: Bio electronics** **Chairperson** **Beomjoon Kim (University of Tokyo)** **Shigenori Aoki (LINTEC Corporation)**	
13:00	Thermal Conductivity Aware Design Approach of Non-Conductive Film Layers for Enhanced Vertical Heat Dissipation in 3D HBM Packages *Yuna Lee, Sang Won Yoon* *Seoul National University*	09-01	**(Invited)** Efficient AI System Scale-Up with Optical Interconnect: Opportunities & Challenges *Sunil Priyadarshi* *Arista Networks*	10-01	**(Invited)** Development of a Rumen Bacteria Microbial Fuel Cell for Cattle Health and Methane Emission Monitoring Devices *Michitaka Yamamoto, Jarred W. Fastier-Wooller, Shun Muramatsu, Toshihiro Itoh* *The University of Tokyo*	11-01
13:25	A Novel Negative-Tone Chemically Amplified Photoresist of High Resolution and Chemical Resistance for Fine Copper Wirings *Yuanfei Liu, Masahiko Ebihara, Irwansyah, Masahiro Miyasaka* *Resonac*	09-02	Application of graphene-doped polymer optical waveguides to wavelength convertor *Ken Kuboyama1), Naoki Yamaguchi2), Sze Yum Set2), Shinji Yamashita2), Takaaki Ishigure1)* *1) Keio University* *2) The University of Tokyo*	10-02	High Performance X-ray detection module, with Indium bumps interconnections, manufactured on a die level packaging line *Abdenacer AIT MANI, Patrick PERAY, Nadia MILOUD-ALI, Andrea BRAMBILLA, Arnaud PEIZERAT, Kim ABDOUL-CARIME, Loick VERGER* *CEA-LETI*	11-02
13:50	Development of 1.6 µm Fine-Pitch RDL Damascene Process using Low-NA i-Line Stepper and a New Negative-tone Photosensitive Dielectric Material *Lili Wang1), Murat Pak1), Go Inoue2), Kaho Shibasaki2), Ayano Okuda2), Kenyu Sugita2), Nobuhiro Ishikawa2), Toshiyuki Ogata2), Andy Miller1), Eric Beyne1)* *1) imec* *2) TAIYO HOLDINGS CO., LTD*	09-03	Low Wavelength Dependent Polymer Waveguide type Multiplexer for MDM Link *Takumi Kanai, Takaaki Ishigure* *Keio University*	10-03	Fabrication of Flexible Electrochemical Sensor for Interstitial Fluid Biomarker Monitoring using Pattern Transfer Method *Boyu Qin, Jongho Park, Beomjoon Kim* *The University of Tokyo*	11-03
14:15	Study of Structural Evaluation in Fan-Out Large Body Size Packaging *Shuai-Lin Liu, Teny Shih, Vito Lin, Sam Lin, Yu-Po Wang* *Siliconware Precision Industries Co., Ltd.*	09-04	Miniaturization of 1x2 and 1x4 branched multimode polymer optical waveguide for MUX device in SWDM links *Koki Atsumi, Takaaki Ishigure* *Keio University*	10-04		
14:40	*Interview with the Authors (Discussion after the session) + Sponsor's Exhibition*					
14:55	*Coffee break + Sponsor's Exhibition*					
15:10- 15:50	**IEEE EPS Special Speech I** **Hall I** **Chairperson Shinya Takyu (LINTEC Corporation) and Eiji Higurashi (Tohoku University)**					
15:10	**IEEE EPS Special Speech I: Co-Packaged Optics – 3D Heterogeneous Integration of Photonic IC and Electronic IC** ***John H Lau (Unimicron Technology Corporation)***					S-01
15:50- 16:30	**IEEE EPS Special Speech II** **Hall I** **Chairperson Shinya Takyu (LINTEC Corporation) and Eiji Higurashi (Tohoku University)**					
15:50	**IEEE EPS Special Speech II: Aging of Lead-Free Solders** ***Jeffrey C. Suhling (Auburn University)***					S-02

16:40- 17:40	**Early Career Researcher's (ECR) Session (Open Forum with Beer) @ 1F Cafeteria**					
	Chairperson Takaaki Ishigure (Keio University)					
	Poster presentation					
	Packaging Technology for Ion Trap Quantum Processor Chips *Nila Krishnakumar1), Friederike Giebel1), Eike Iseke1), Konstantin Thronberens1), Jacob Stupp2), Nora D. Stahr2), Christian Ospelkaus1),2)* *1) Physikalisch-Technische Bundesanstalt* *2) Gottfried Willhelm Leibniz University*	ECR-01	Automated 5-axis system for mosquito dispensed waveguides *Laura Fuetterer, Andreas Evertz, Ludger Overmeyer* *Leibniz University Hannover*	ECR-02	Investigations into the use of synthetic image data for the automated active alignment of micro-optics *Anna-Lena Fritze, Ludger Overmeyer* *Leibniz University Hannover*	ECR-03
	Direct Thermal Characterization of Thinned InP-Laser Diodes *Kiyoto Taniguchi1),2), Taro Itatani2), Joji Maeda1), Akihiro Noriki2), Takeru Amano2)* *1) Tokyo University of Science* *2) AIST*	ECR-04	Deep Learning with De-embedded S-parameters for Assessing Crack Propagation in Solder Joints *Namgyeong Kim, Minkyu Kang, Hyunwoo Nam, Tae Yeob Kang* *The University of Suwon*	ECR-05	Investigation of Polarization Performance in Polymer Optical Splitters for Co-Packaged Optics *Yudai Nagano1),2), Taro Itatani2), Fumi Nakamura2), Akihiro Noriki2), Takeru Amano2), Joji Maeda1), Satoshi Suda2)* *1) Tokyo University of Science* *2) National Institute of Advanced Industrial Science and Technology*	ECR-06
	3-D Optical Interconnection of Bent Waveguides and Micro-Mirror by Planar Semiconductor Process *Keito Kikuchi1),2), Taro Itatani2), Yoshinobu Okano1), Akihiro Noriki2), Takeru Amano1),2)* *1) Tokyo City University* *2) AIST*	ECR-07	Non-destructive Diagnosis of Cracks in SMD Capacitors Using Deep Learning on Impedance Spectra *Minkyu Kang, Namgyeong Kim, Hyunwoo Nam, Tae Yeob Kang* *The University of Suwon*	ECR-08	Quantum dot doped polymer optical waveguide amplifier *Hayato Kitta, Takaaki Ishigure* *Keio University*	ECR-09
	Core Position Accuracy Improvement of Polymer Optical Waveguide fabricated using the Mosquito-Method *Airi Nakao, Takaaki Ishigure* *Keio University*	ECR-10	Steeply bent core single-mode polymer waveguide with low bending loss fabricated using the Mosquito method *Ayu Tanimoto, Takaaki Ishigure* *Keio University*	ECR-11	Investigation of surface activation conditions using VUV light to enable room-temperature Au–Au bonding *Mika Ogino, Kai Takeuchi, Eiji Higurashi* *Tohoku University*	ECR-12
	Multi-Sensor Integrated Urethane Foam Package for Wearable Vital Sensing in Everyday Setting *Suguru Sato, Naoto Tomita, Jarred Fastier-Wooller, Shun Muramatsu, Michitaka Yamamoto, Toshihiro Itoh* *The University of Tokyo*	ECR-13				
17:40	*Close*					

November 14, 2025 (Friday)

	4F/5F Main Hall		**1F Room I**		**1F Room II**	
9:00	*Registration*					
9:20	*ECR Award Ceremony*					
9:30- 10:10	**Special Speech II** **Hall I** **Chairperson Shoji Uegaki (Crane Research) and Shinya Takyu (LINTEC Corporation)**					
9:30	**Special Speech II: Innovative AI for Advanced Packaging Solutions** ***C.P. Hung (ASE Group)***					S-05
10:10- 10:50	**Special Speech III** **Hall I** **Chairperson Taiji Sakai (TSMC Japan 3DIC R&D Center, Inc.) and Kenji Takahashi (AIST)**					
10:10	**Special Speech III: Advanced Packaging Technologies Enabling AI Semiconductors at Applied Materials** ***Noriaki Matsunaga (Applied Materials Japan)***					S-04
10:50	*Coffee break + Sponsor's Exhibition*					
11:05- 12:35	**Session 12: IEEE EPS Technical session** **-Substrate and Polymer Waveguide for CPO-** **Chairperson** **Shigenori Aoki (LINTEC Corporation)** **Takashi Hisada (Rapidus)**		**Session 13: Advanced PKG III** **Chairperson** **Chinami Marushima (IBM Japan, Ltd.)** **Shoji Uegaki (Crane Research)**		**Session 14: Power Electronics I** **Chairperson** **Kentaro Kaneko (Ritsumeikan University)** **Masafumi Yokoyama (SUMITOMO CHEMICAL COMPANY, LIMITED)**	
11:05	**(Invited)** Active optical package substrate with polymer waveguide optical RDL for next generation CPO *Akihiro Noriki* *AIST*	12-01	Laser-Induced Forward Transfer of Thin Micro-Chiplets in quasi-contact mode *Harindra Kumar Kannojia, Geert Van Steenberge* *IMEC and Ghent University*	13-01	**(Invited)** Wafer Bonding of Diamond for Improving Heat Dissipation of Properties of Nitride Devices *Naoteru Shigekawa, Jianbo Liang, Yutaka Ohno* *Osaka Metropolitan University*	14-01
11:30	**(Invited)** Fiber-to-chip self-coupling based on near-infrared self-written optical waveguide *Hidetaka Terasawa* *Utsunomiya University*	12-02	Non-Invasive Corrosion Quantification in Electronic Packages Using Smith Charts *Tae Yeob Kang, Namgyeong Kim, Minkyu Kang* *The University of Suwon*	13-02	Material and Process Characterization to Enable Heavy Copper Wire Bonding on Power Modules *Randolph Flauta1), Jing Chen2), Howie Ding2), Rito Wang2), Shixing Zhu2), Tino Minotti3), King Man Tai1), Joe Zhou2), Haibin Chen4)* *1) Nexperia HK* *2) Nexperia China* *3) Nexperia Italy* *4) HKUST*	14-02
11:55	*Interview with the Authors (Discussion after the session) + Sponsor's Exhibition*		**(Invited)** Advanced Packaging Technologies for Modular and Powerful Compute *Kazuyuki Irie* *GUC Japan*	13-03	Study of Factor Effect on Surge Current Test Performance for Clip-Bonded Semiconductor Devices by Simulation *Nick Chenchao ZHONG1), Thomas IGEL-HOLTZENDORFF2), Haibo FAN1), Tim BOETTCHER2), Owen Yi Kei LAW1)* *1) Nexperia Hong Kong* *2) Nexperia Hamburg*	14-03
12:20	*Interview with the Authors (Discussion after the session) + Sponsor's Exhibition*					
12:35- 13:40	*Lunch (free time)*					
13:40- 15:35	**Session 15: Photonics IV** **(Optical connection)** **Chairperson** **Junichi Inoue (Kyoto Institute of Technology)** **Takaaki Ishigure (Keio University)**		**Session 16: Power Electronics II** **Chairperson** **Kentaro Kaneko (Ritsumeikan University)** **Hiroki Imabayashi (University of Fukui)**			
13:40	**(Invited)** Accelerating the Future: Silicon Photonics and Advanced Packaging at the Heart of HPC *Sandeep Sane* *Lightmatter*	15-01	**(Invited)** Development of Planar-Gate Vertical GaN MOSFETs *Ryo Tanaka, Tsurugi Kondo, Nao Suganuma, Katunori Ueno, Shinya Takashima* *Fuji Electric Co.,Ltd.*	16-01		
14:05	40-channel Detachable Optical Connector Enabling Ultra-high Density Connectivity in Co-packaged Optics *Yuki Fujimaki, Shosuke Ikeda, Kengo Watanabe, Tsunetoshi Saito, Masaki Kotoku* *Furukawa Electric Co., Ltd.*	15-02	EMI Mitigation and Inductance Reduction in SiC Power Modules through Layout Optimization *Raymond Borres1), Thiyu Warnakulasooriya1), Sihoon Choi1), Koichi Shigematsu1), Masayoshi Yamamoto1), Ang-Ying Lin2), Yan Bo Fang2), Chien Wei Chang2), Po-Kai Chiu2), Yan-Cheng Liu2)* *1) Nagoya University* *2) Industrial Technology Research Institute*	16-02		
14:30	Single Mode Multifiber Expanded Beam Connector for Immersion Cooling System Using GRIN Lens *Alexander William Setiawan Putra1), Yusuke Ishibashi1), Motohito Takezaki1), Kazutaka Aboshi2)* *1) Hakusan Inc.* *2) Nippon Sheet Glass Co., LTD.*	15-03	Research on low thermal resistance/high reliability technology for ultra-compact double-sided cooled SiC power modules *Akira Kitamura, Yoshihiro Tateishi, Shoichiro Otani, Satoharu Tanai, Keita Suzuki, Tetsuo Endoh, Yoshikazu Takahashi* *TOHOKU UNIVERSITY*	16-03		
14:55	Evaluation of fabricating polymer waveguides for die-to-die optical connections *Honoka Shima, Masaharu Kato, Kazunao Yamamoto, Masaki Matsumoto, Yuji Furuta, Hisashi Kaneda* *SHINKO ELECTRIC INDUSTRIES CO., LTD.*	15-04	Additive fan-out packaging for discrete components *Edsger C.P. Smits1),2), Arjun Wadhwa2), Milan Saalmink2), Marieke Burghoorn2), Iris Kerkhof2), Ruben Pranger1),2), Frans Meeuwsen1),2), Francesca Chiappini1),2), Jeroen van den Brand2)* *1) CITC* *2) TNO*	16-04		
15:20	*Interview with the Authors (Discussion after the session)*					
15:35	*Close*					